

Title (en)  
APPARATUS AND METHOD FOR APPLYING FLUX TO A SUBSTRATE

Title (de)  
VORRICHTUNG UND VERFAHREN ZUM AUFTRAGEN VON FLUX AUF EIN SUBSTRAT

Title (fr)  
DISPOSITIF ET PROCEDE PERMETTANT D'APPLIQUER DU FLUX A UN SUBSTRAT

Publication  
**EP 1156886 A4 20020828 (EN)**

Application  
**EP 00902365 A 20000107**

Priority  
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• US 22724399 A 19990107

Abstract (en)  
[origin: WO0040343A1] An apparatus and method is provided for applying a liquid solder flux in a pattern to a substrate. A stencil is utilized which comprises first apertures (16) corresponding in location to the pattern and second apertures (32) in fluid communication with the first apertures, the second apertures being disposed adjacent an upper surface of the substrate. The first apertures are disposed in a first section (26) of the stencil and the second apertures are disposed in a second section (28) of the stencil. The first section (26) and the second section (28) meet at a planar intersection substantially parallel to first and second sides of the stencil. The planar intersection has a cross section different from that of the first and second sections.

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CPC (source: EP)  
**B23K 1/203** (2013.01); **H05K 3/1225** (2013.01); **G03F 7/12** (2013.01)

Citation (search report)  
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• [XA] PATENT ABSTRACTS OF JAPAN vol. 016, no. 579 (E - 1299) 18 December 1992 (1992-12-18)  
• [X] PATENT ABSTRACTS OF JAPAN vol. 016, no. 059 (E - 1166) 14 February 1992 (1992-02-14)  
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• See references of WO 0040343A1

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